



Material Content Data Sheet



Sales Product Name		TLV4961-1TB		Issued		24. January 2018			
MA#		MA001296432							
Package		PG-TO92S-3-2		Weight*		126.87 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.350	0.28	0.28	2755	2755	
leadframe	non noble metal	iron	7439-89-6	0.091	0.07		717		
	inorganic material	phosphorus	7723-14-0	0.027	0.02		215		
	non noble metal	copper	7440-50-8	90.909	71.66	71.75	716527	717459	
wire	noble metal	gold	7440-57-5	0.029	0.02	0.02	229	229	
encapsulation	organic material	carbon black	1333-86-4	0.089	0.07		701		
	plastics	epoxy resin	-	2.727	2.15		21492		
	inorganic material	silicondioxide	60676-86-0	26.823	21.14	23.36	211416	233609	
leadfinish	non noble metal	tin	7440-31-5	5.498	4.33	4.33	43334	43334	
plating	noble metal	silver	7440-22-4	0.153	0.12	0.12	1206	1206	
glue	plastics	epoxy resin	-	0.036	0.03		282		
	noble metal	silver	7440-22-4	0.143	0.11	0.14	1126	1408	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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